ABSTRACT

A MOULD FOR INTEGRATED CIRCUIT ENCAPSULATION

A mould for integrated circuit encapsulation is disclosed comprising first and second mould sections 112, 114 having respective first and second clamping surfaces 130, 132 engageable under pressure on either side of an integrated circuit lead frame. The cross sectional area of the upper clamping surface 130 is less than the cross sectional area of the lower clamping surface 132 and the outer peripheral edge of the lower clamping surface 132 project beyond the outer peripheral edge of the upper clamping surface 130.

Figures 5a and 5c